Preface ICAMEM 2021

Dear Distinguished Authors and Guests,

It was a great pleasure to welcome all participants in the 2021 10th International Conference on Advanced Materials and Engineering Materials (ICAMEM 2021), held on May 29-30, 2021 (virtual).

ICAMEM2021 aims at sharing new ideas and new technologies amongst the professionals, industrialists and students from research areas of Advanced Materials and Nanotechnology to share their recent innovations and applications and indulge in interactive discussions and technical sessions at the event.

ICAMEM, initiated from 2011, has been successfully held 9 editions in various locations, including Shenyang (2011), Beijing (2012), Singapore (2013, 2017), Ningbo & Hongkong (2014), Hong Kong (2016, 2019), Thailand (2018) and online (due to COVID-19 in 2020). More than 3000 participants have been attracted from over 50 countries and regions in the previous 9 years. Participations in the conference has increased significantly over the years and the conference has become truly international.

On behalf of the organizing committee, the editor would like to acknowledge the technical comments from the reviewers and thank all of the authors for their contributions to this proceeding book.

With our warmest regards,

Conference Organizing Chair
Prof. Peng-Sheng Wei
National Sun Yat-Sen University, Kaohsiung, Taiwan
June 23, 2021

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